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Electronic Patent Application Submission
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EFS ID: 24717
Application ID: 09687048
Title of Invention: LEADFRAME AND
SEMICONDUCTOR PACKAGE WITH
IMPROVED SOLDER JOINT
STRENGTH
First Named Inventor: Kuri-Shi Lee
Domestic/Foreign Application: Domestic Application
Filing Date: 2000-10-13
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Attorney Docket Number: AMKOR-052A
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Submission Type: Information
Disclosure Statement

Application Number: 09/687,048

Attorney Docket Number: AMKOR-052A

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

First Named Inventor: Kuri-Shi Tae Heon Lee

SUBMITTED BY

Name: Mark B. Garred
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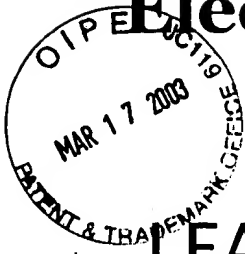
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Electronic Information Disclosure Statement

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

Application:



09/687048

Confirmation: 1120

Applicant(s): Kuri-Shi Lee

Docket

AMKOR-052A

Number:

Group Art

2814

Unit:

Examiner:

Dilinh P. Nguyen

(5703407 or 5696666 or 5689135 or 5683806 or 5673479 or 5665996 or 5650663 or 5646831 or 5644169 or 5641997 or 5640047 or 5639990 or 5633528 or 5625222 or 5608267 or 5604376 or 5594274 or 5592025 or 5581122 or 5545923 or 5544412 or 5543657 or 5539251 or 5534467 or 5517056 or 5508556 or 5493151 or 5474958 or 5454905 or 5444301 or 5435057 or 5424576 or 5414299 or 5410180 or 5406124 or 5391439 or 5343076 or 5336931 or 5335771 or 5332864 or 5327008 or 5294897 or 5279029 or 5277972 or 5273938 or 5266834 or 5258094 or 5252853 or 5250841 or 5221642).pn.

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